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ADVANCED IC PACKAGING TECHNOLOGIES, MATERIALS, AND MARKETS

2016 EDITION

A Strategic Report Covering the Latest Technologies in IC Packaging, Enabling Portable and Other Electronics

Report Coverage

- **Stacked Packages**
- **System-in-Packages**
- **Interconnection Technologies**
- **Through-Silicon-Vias (TSV)**
- **2.5D and 3D Integration**
- **Multi-row QFNs**
- **Fan-out WLPs**

Report Highlights

- **Industry Outlook**
- **Market Analysis and Forecasts, 2014–2020**
- **Multichip Packaging Technology Trends**
- **Key Application Forecasts**
- **Company Profiles**

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Advanced IC Packaging Technologies, Materials, and Markets, 2016 Edition

Synopsis

The demand for consumer electronics and mobile communications devices that keep us connected is driving electronics manufacturers to deliver ever-more compact and portable electronic systems. Today's users ask for products with more functionality, added performance, higher speed, and smaller form factors. Advances in IC packaging technologies are providing solutions to meet these demands through a variety of techniques that result in ICs that are more powerful and provide greater functionality, while fitting into ever smaller and more highly integrated form factors. Multichip packages are on the leading edge of silicon integration, while advances in interconnection and substrate design are providing additional opportunities to improve package density. The future is bright for IC packaging.

This latest report from **New Venture Research (NVR)**, ***Advanced IC Packaging Technologies, Materials and Markets, 2016 Edition***, captures the latest technology and market trends of the IC packaging industry by focusing on the most advanced packaging products and technologies - those most critical to success in developing cutting-edge products and maintaining technological leadership.

Chapter 3: Overview of IC Packaging Markets Worldwide , outlines the major IC packaging families and the latest market and application trends. Total market forecasts include units, prices, packaging revenue, package types and device types.

Chapter 4: Advanced IC Packaging, provides an in-depth discussion of the two leading advanced packages: Fan-Out Wafer Level and Multi-Row QFN packages in terms of market overview and market trends and forecasts.

Chapter 5: Multichip Packages, offers descriptions of 3D stacked packages (TSOPs, BGA/FBGAs, QFNs and WLPs), interconnection, as well as advanced multicomponent packages (PoPs, PiPs, and MCMs). Forecasts include multichip IC packaging units, revenue, prices, die usage and applications.

Chapter 6: System in Package (SiP) Solutions & Substrate Materials, presents a more in-depth look at the evolving multicomponent packages, and presents key market trends alongside forecasts of units and revenue. This chapter also examines the substrate materials and embedded components used in SiP assembly. Forecasts include package units and material area shipped, as well as revenue impact of substrate material trends.

Chapter 7: Interconnection Techniques, provides an in-depth explanation of wire bonding and flip chip markets, as well as leading-edge technologies, such as 2.5D and 3D packaging using through silicon vias (TSVs). Units and revenue forecasts are provided.

Chapter 8: Company Profiles examines twenty of the leading companies making advanced packages today. Each profile gives a short company background and presents examples of their advanced packaging products.

Advanced IC Packaging Technologies, Materials and Markets, 2016 Edition is an effective tool for companies determined to stay informed about the latest advances in IC packaging technologies, and in assessing the future of this important segment of the semiconductor manufacturing industry. The report sells for $3995 and is delivered by email as a single-user license PDF file. Additional single-user licenses are available for $350 each and a corporate license is $1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional $1000, or a printed copy may be purchased for $250.

About the Author

Jerry Watkins is an independent senior analyst with more than 25 years of experience in the field of market research and consulting. He has worked for leading research companies such as **Frost & Sullivan**, **Lucid Information Services**, and **NSI Research** both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications sector and more recently in the computing and merchant embedded computing industry. He holds three university degrees, including a B.A. in History, as well as a M.A. in International Studies.

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